

Council Honorary Chair:

Yu Yao, Harbin Engineering University, China

Advisory Council Honorary Chairs:

T. J. Tarn, Washington University, USA

Toshio Fukuda, Nagoya University, Japan

Advisory Council Chairs:

Tianyou Chai, Northeastern University, China

Raja Chatila, Univ. Pierre and Marie Curie, France

Kazuhiro Kosuge, The Univ. of Hong Kong, China

Paolo Dario, Scuola Superiore Sant'Anna, Italy

Masayoshi Tomizuka, UC Berkeley, USA

Mario A. Rotea, University of Massachusetts, USA

Ju-Jang Lee, KAIST, Korea

Jonathon A. Chambers, University of Leicester, UK

Yanrong Li, UESTC, China

Huadong Yu, Jilin University, China

Jijian Lian, Tianjin University of Tech., China

Yuxin Zhao, Harbin Engineering University, China

General Chairs:

Darwin G. Caldwell, Italian Institute of Tech., Italy

Yonggang Zhang, Harbin Engineering Univ., China

General Co-Chairs:

William R. Hamel, University of Tennessee, USA

James K. Mills, University of Toronto, Canada

Hajime Asama, University of Tokyo, Japan

Andrew F. Laine, Columbia University, USA

Henrik Hautop Lund, Technical Univ. of Denmark

Tao Zhang, Tsinghua University, China

Jinhu Lv, Beihang University, China

Yuanqing Xia, Beijing Institute of Technology, China

Ming Yang, Shanghai Jiao Tong University, China

Chunhua Yang, Central South University, China

Zhigang Zeng, Huazhong Univ. of Science and Tech.

Min Wu, China Univ. of Geosciences, Wuhan, China

Danilo Mandic, Imperial College London, UK

Lyudmila S. Mihaylova, The Univ. of Sheffield, UK

Mingxing Du, Tianjin University of Technology, China

Shijie Guo, Hebei University of Technology, China

Program Chair:

Xiufen Ye, Harbin Engineering University, China

Program Co-Chairs:

Kevin Lynch, Northwestern University, USA

Qing Zhao, University of Alberta, Canada

Wan Kyun Chung, POSTEC, Korea

Hiroshi Toshiyoshi, University of Tokyo, Japan

Arianna Menciassi, Scuola Superiore Sant'Anna, Italy

Koichi Hashimoto, Tohoku University, Japan

Jianwei Zhang, University of Hamburg, Germany

Anqi Qiu, National Univ. of Singapore, Singapore

Wei Zhang, Harbin Engineering University, China

Peng Shi, Henan Univ. of Science and Tech., China

Liwei Shi, Beijing Institute of Technology, China

Yang Zhao, Xiamen University, China

Organizing Committee Chairs

Shuxiang Guo, Kagawa Univ./BIT/SUSTech

Hongbo Li, Harbin Engineering University, China

Organizing Committee Co-Chairs

Yili Fu, Harbin Institute of Technology, China

Aiguo Ming, UEC, Japan

Yulong Huang, Harbin Engineering University, China

Xueshan Gao, Beijing Institute of Tech., China

Tutorials/Workshop Chairs:

Nak Youn Chong, JAIST, Japan

Xuping Zhang, Aarhus University, Denmark

Songyuan Zhang, Harbin Institute of Tech., China

Invited/Organized Session Chairs:

Kazuhiro Yokoi, AIST, Japan

Zhilin Liu, Harbin Engineering University, China

Jinjun Shan, York University, Canada

Longqing Cong, SUSTech, China

Awards Committee Co-chairs

Hong Zhang, Southern U. of Science and Tech., China

Xinkai Chen, Shibaura Institute of Tech., Japan

Publications Chair:

Jin Guo, Beijing Institute of Technology, China

Yuefei Cai, SUSTech, China

Publicity Chairs:

Xueyi Tian, Harbin Engineering University, China

Guangjun Liu, Toronto Metropolitan Univ., Canada

Changsheng You, SUSTech, China

Finance Chairs:

Jian Guo, Tianjin University of Technology, China

Ziqian Chen, Harbin Engineering University, China

Local Arrangement Chair:

Huiming Xing, Harbin Engineering University, China

Secretariats:

Z.Y. Yang, Chunying Li, Ximing Li, Kagawa U., Japan

Sheng Cao, He Li, Yonggan Yan, BIT, China



IEEE ICMA 2023

2023 IEEE International Conference on Mechatronics and Automation August 6-9, 2023, Harbin, China



IEEE



Robotics & Automation Society



Co-sponsors: IEEE Robotics and Automation Society, Harbin Engineering University, Beijing Inst. of Tech.

Technical Co-sponsors: NSFC, CAA, RSJ, JSME, SICE, JSPE, UEC, UESTC, TJUT, JLU, SUSTech

Call for Papers



Index

The 2023 IEEE International Conference on Mechatronics and Automation (ICMA 2023) will take place in Harbin, China from August 6 to August 9, 2023. A renowned ancient city in China, Harbin is situated in northeastern China. As the capital of Heilongjiang province, the city boasts the largest historical museum of the Jin Dynasty, remains of the Huining Mansion and the tombs of Wanyanaguda. As the host city of ICMA 2023, Harbin not only provides the attendees with a great venue for this event, but also an unparalleled experience in Chinese history and culture. You are cordially invited to join us at IEEE ICMA 2023 in Harbin to live this unique experience. The objective of ICMA 2023 is to provide a forum for researchers, educators, engineers, and government officials involved in the general areas of mechatronics, robotics, automation and sensors to disseminate their latest research results and exchange views on the future research directions of these fields.

The topics of interest include, but not limited to the following:

- Intelligent mechatronics, robotics, biomimetics, automation, control systems,
- Opto-electronic elements and Materials, laser technology and laser processing
- Elements, structures, mechanisms, and applications of micro and nano systems
- Teleoperation, telerobotics, haptics, and teleoperated semi-autonomous systems
- Sensor design, multi-sensor data fusion algorithms and wireless sensor networks
- Biomedical and rehabilitation engineering, prosthetics and artificial organs
- Control system modeling and simulation techniques and methodologies
- AI, intelligent control, neuro-control, fuzzy control and their applications
- Industrial automation, process control, manufacturing process and automation

Contributed Papers: All papers must be submitted in PDF format prepared strictly following the IEEE PDF Requirements for Creating PDF Documents for IEEE Xplore. The standard number of pages is 6 and the maximum page limit is 8 pages with extra payment for the two extra pages. See detailed instructions in the conference web site. All papers accepted will be indexed by EI and all conference content will be submitted for inclusion into IEEE Xplore®. Extensions of selected papers will be published in a regular or a special issue of the journals of **IJMA**.

Organized Sessions: Proposals with the title, the organizers, and a brief statement of purpose of the session must be submitted to an OS Chair by April 10, 2023.

Tutorials & Workshops: Proposals for tutorials and workshops that address related topics must be submitted to one of the Tutorial/Workshop Chairs by May 1, 2023.

Important Dates:

April 10, 2023	Full papers and organized session proposals
May 1, 2023	Proposals for tutorials and workshops
May 15, 2023	Notification of paper and session acceptance
June 1, 2023	Submission of final papers in IEEE PDF format

For detailed up-to-date information, please visit the IEEE ICMA conference website at:

<http://2023.ieee-icma.org>